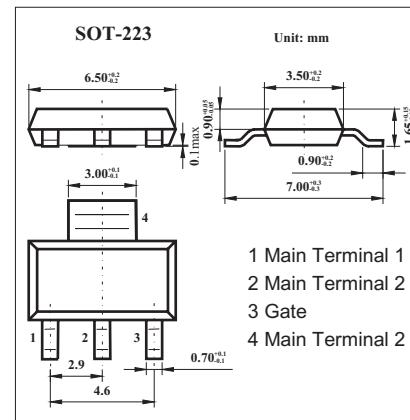
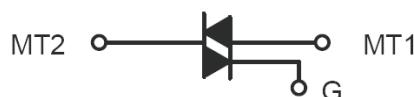


Sensitive Gate Triacs

MAC08BT1, MAC08MT1

■ Features

- Sensitive Gate Trigger Current in Four Trigger Modes
- Blocking Voltage to 600 Volts
- Glass Passivated Surface for Reliability and Uniformity
- Surface Mount Package



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Peak Repetitive Forward and Reverse Blocking Voltage* MAC08BT1 MAC08MT1	V _D R _M and V _R R _M	200 600	V
Forward Current RMS	I _T (RMS)	0.8	A
Peak Forward Surge Current, TA = 25°C	I _T SM	8.0	A
Circuit Fusing Considerations (t = 8.3 ms)	I ² t	0.4	A ² s
Peak Gate Power — Forward, TA = 25°C	P _G M	5.0	W
Average Gate Power — Forward, TA = 25°C	P _G F(AV)	0.1	W
Thermal Resistance, Junction to Ambient	R _θ JA	156	°C/W
Lead Solder Temperature(<1/16"from case, 10 s max)		230	°C
Operating Junction Temperature Range @ Rated V _R R _M and V _D R _M	T _J	-40 to +110	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

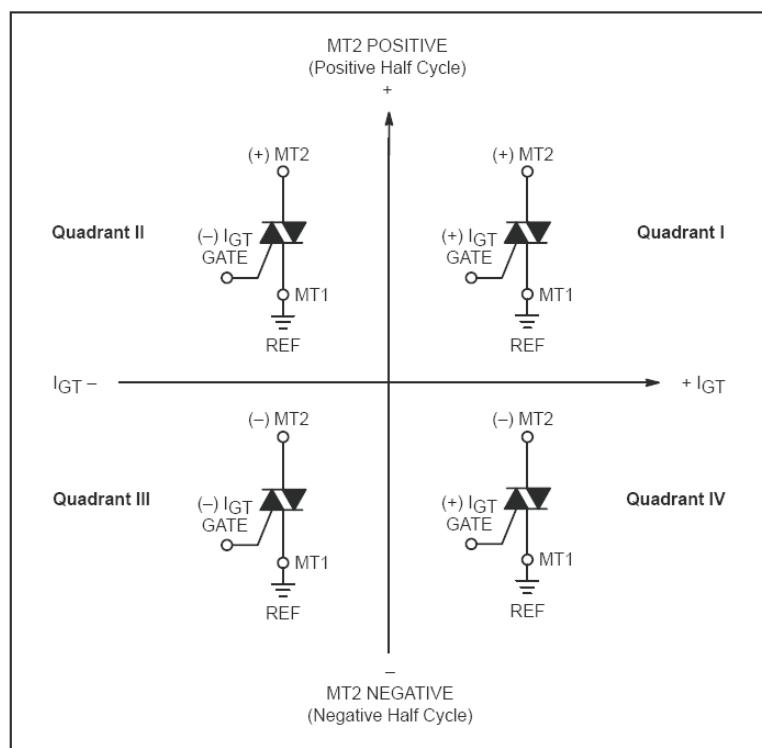
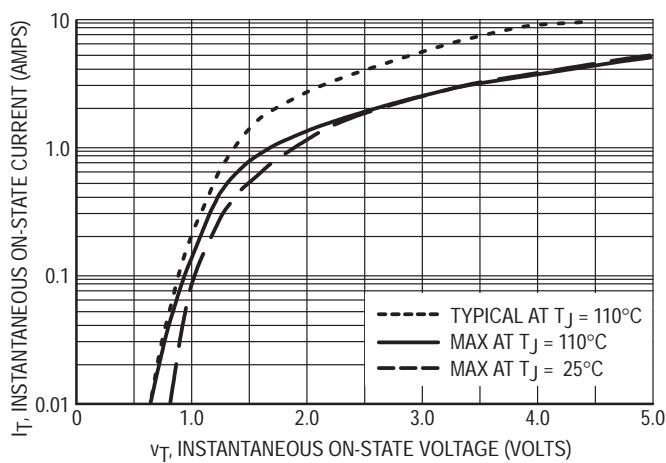
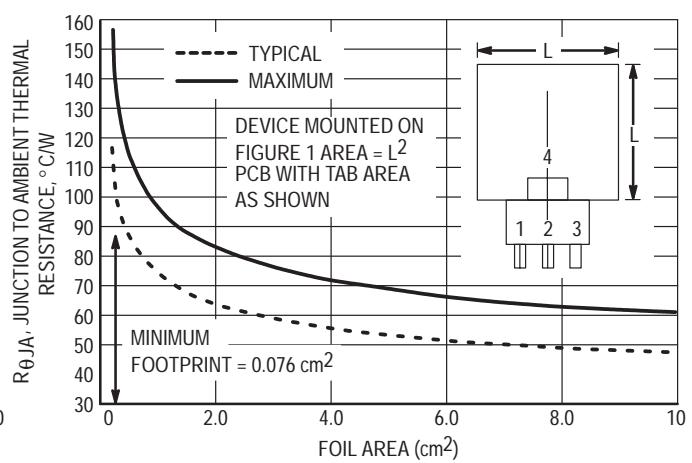
*T_J = 25 to 125°C, R_{GK} = 1 kΩ

■ Electrical Characteristics (Ta = 25°C, RGK = 1 kΩ unless otherwise noted.)

Parameter	Symbol	Testconditons	Min	Max	Unit
Peak Forward or Reverse T _c = 25°C Blocking Current T _c = 110°C	I _D R _M , I _R R _M	V _A K = Rated V _D R _M or V _R R _M		10 200	μA
Forward "On" Voltage*1	V _{TM}	I _T M = ±1.1 A Peak @ TA = 25°C		1.9	V
Gate Trigger Current (Continuous dc)*2 T _c = 25°C	I _{GT}	V _D =12 V, R _L = 100 Ohms		10	mA
Gate Trigger Voltage (Continuous dc)	V _{GT}	V _D =12V,R _L =100 Ohms		2.0	V
Holding Current	I _H	V _D =12V, Gate Open, initiating current=±20mA		5	mA
Critical Rate of Rise of Commutation Voltage *	(dv/dt)c		1.5		V/ μ s
Critical Rate of Rise of Off State Voltage	dv/dt	V _{pk} = Rated V _D R _M , T _c = 110°C, Gate Open, Exponential Method	10		V/ μ s

* f = 250 Hz, I_TM = 1.0 A, Commutating di/dt = 1.5 A/mS On-State Current Duration = 2.0 mS,

V_DR_M = 200 V, Gate Unenergized, T_c = 110°C, Gate Source Resistance = 150 Ω, See Figure 10)

MAC08BT1, MAC08MT1**Figure 1. Quadrant Definitions for a Triac****■ Typical Characteristics****Figure 2. On-State Characteristics****Figure 3. Junction to Ambient Thermal Resistance versus Copper Tab Area**

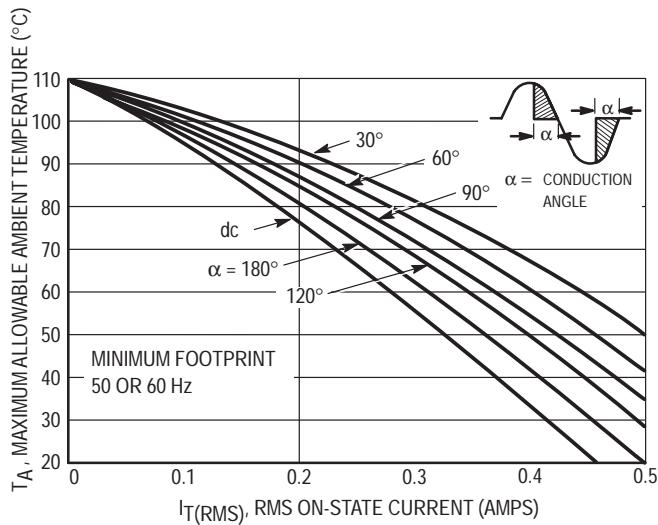
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Figure 4. Current Derating, Minimum Pad Size
Reference: Ambient Temperature

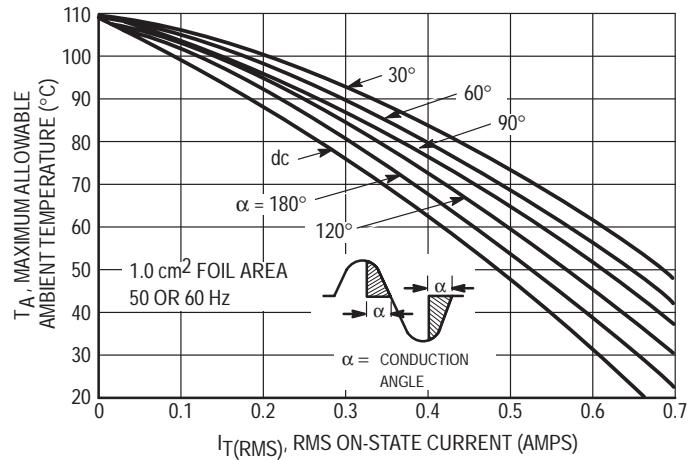


Figure 5. Current Derating, 1.0 cm² Square Pad
Reference: Ambient Temperature

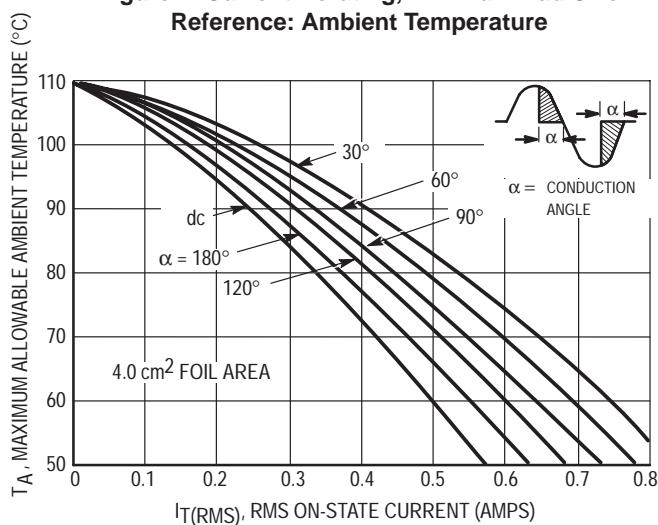


Figure 6. Current Derating, 2.0 cm² Square Pad
Reference: Ambient Temperature

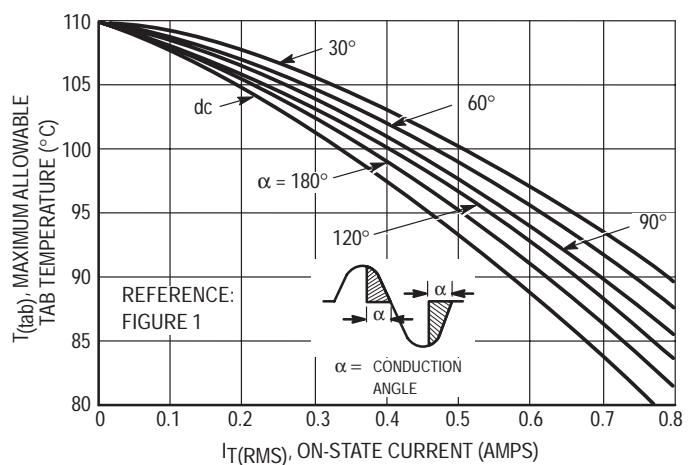


Figure 7. Current Derating
Reference: MT2 Tab

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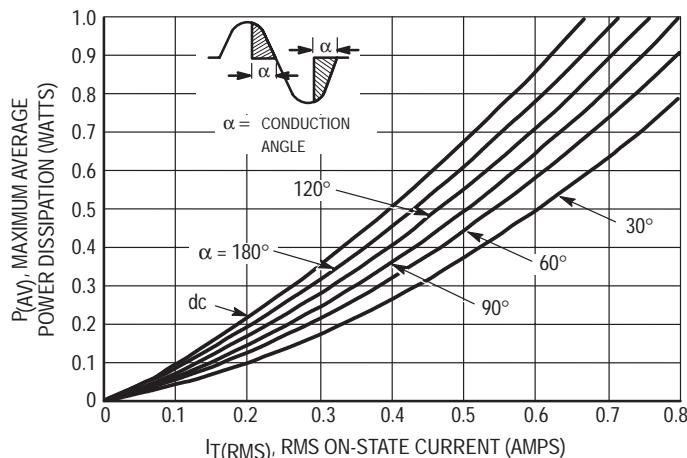


Figure 8. Power Dissipation

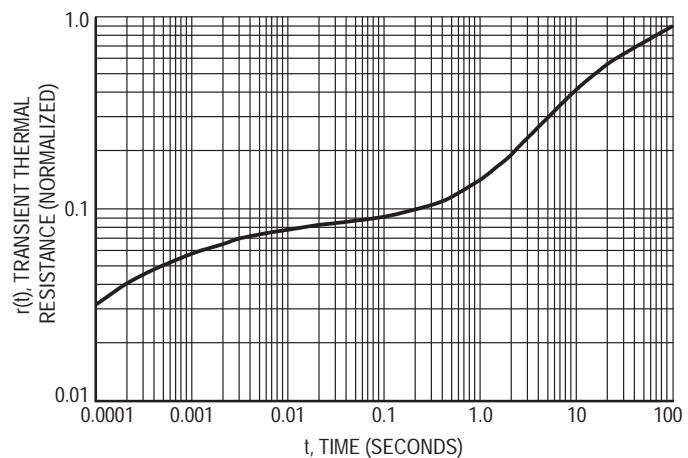
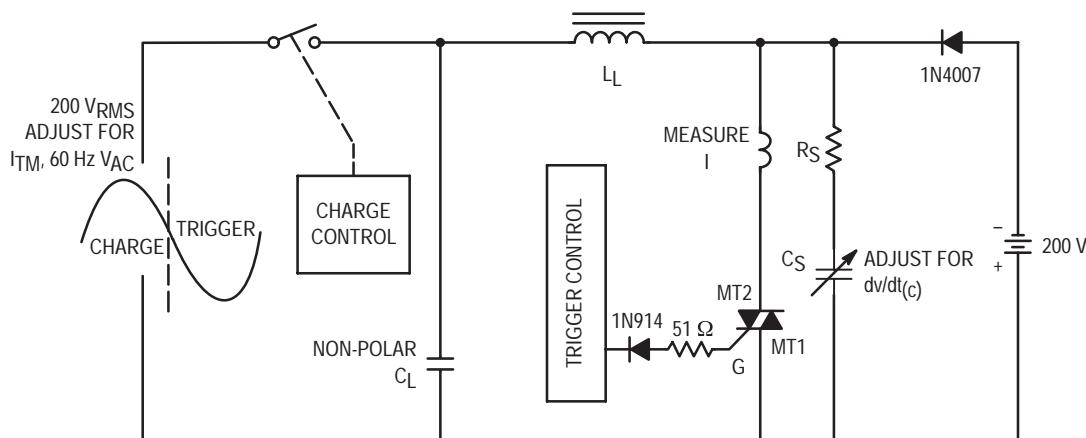
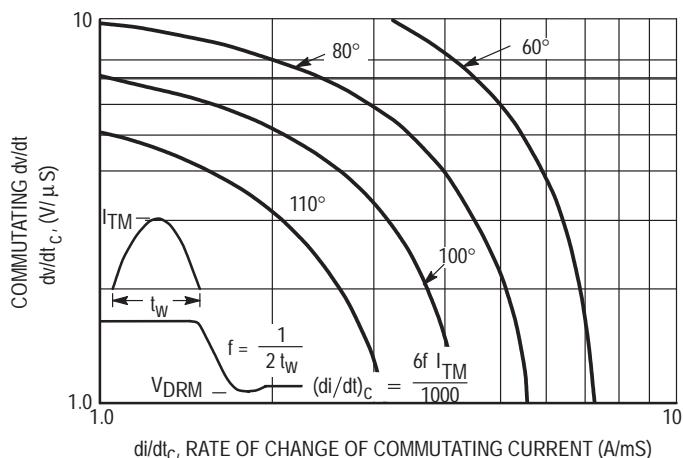
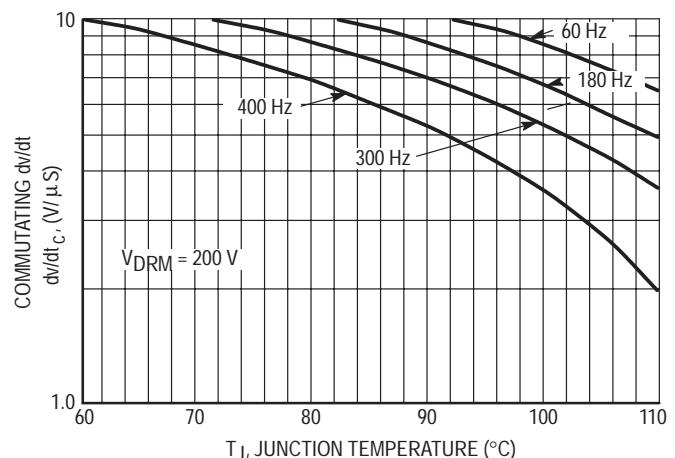


Figure 9. Thermal Response, Device Mounted on Figure 1 Printed Circuit Board



Note: Component values are for verification of rated $(dv/dt)_C$. See AN1048 for additional information.

Figure 10. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Voltage ($dv/dt)_C$ Figure 11. Typical Commutating dv/dt versus Current Crossing Rate and Junction TemperatureFigure 12. Typical Commutating dv/dt versus Junction Temperature at 0.8 Amps RMS

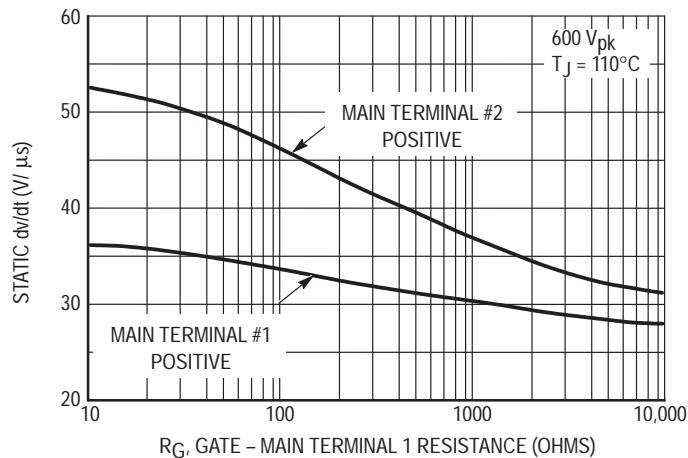
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Figure 13. Exponential Static dv/dt versus Gate - Main Terminal 1 Resistance

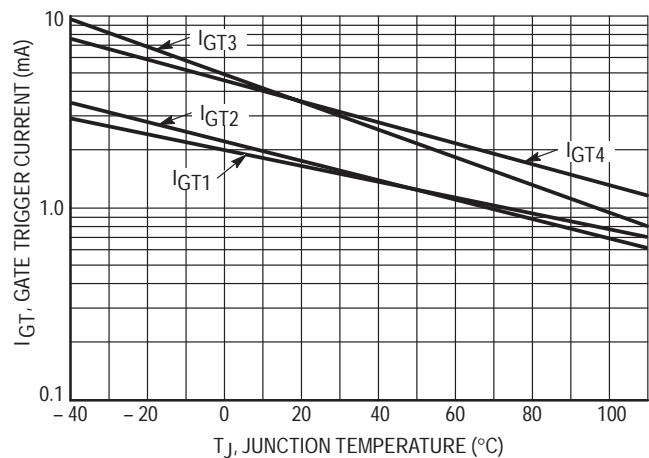


Figure 14. Typical Gate Trigger Current Variation

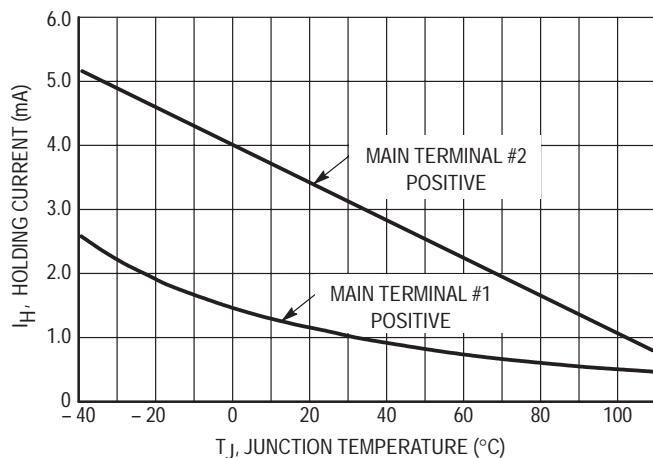


Figure 15. Typical Holding Current Variation

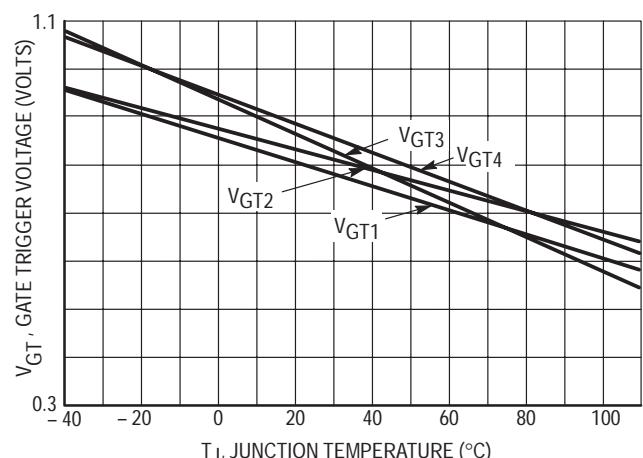


Figure 16. Gate Trigger Voltage Variation